

## Abstract

Provision of a releasing layer transfer film which can form, in a simple manner, a releasing layer on a COF flexible printed wiring board, the releasing layer preventing melt adhesion of an insulating layer to a heating tool, thereby enhancing productivity and reliability of semiconductor devices produced by use of a semiconductor chip mounting line.

The releasing layer transfer film 1 for forming a releasing layer onto an insulating layer serving as a component layer of a COF flexible printed wiring board, the releasing layer transfer film includes a transfer film substrate 2 and a transferable releasing layer 3 provided on a surface of the transfer film substrate 2, wherein the transferable releasing layer 3 is formed from a releasing agent and can be transferred onto the insulating layer.